



TENSOR BLF

Synthetic Slurry Additive for Back-Lapping Wafers

TENSOR BLF is a synthetic polymer surfactant mixture that forms a completely stable abrasive slurry when mixed with de-ionized water and abrasive material. This specialized formulation was developed for optimum surface finish, precise geometry and minimized wafer stress (much less than the stress induced by fixed abrasive back-grinding). TENSOR BLF can also help to eliminate any corrosion of exposed metals during the process. It is used at economical dilutions, is low foaming and an economically attractive method to optimize a thinning process. Singulation processes will yield better results when TENSOR BLF is used to back-lap wafers prior to dicing.

Benefits:

- Better surface finishes
- Consistent removal rates
- Less stress exhibited by lapping
- Non-staining
- Protects Al/Cu and Cu exposed metals

Directions:

TENSOR BLF is designed for use as follows:

79% DI water, 18% 7 micron aluminum oxide, 3% TENSOR BLF.

Mix the Aluminum Oxide with water under high speed agitation (750 RPM) for 10 minutes. Add TENSOR BLF and continue mixing for 10 minutes. Turn off the mixing. The slurry is 100% consistent for 12 hours.

Additional Information:

TENSOR Products are available in 5-gallon pails and 55-gallon drums, F.O.B. Bethel, Connecticut, and also include many application specific chemicals for semiconductor processing. Material Safety Data Sheets available upon request.

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